

FEATURES

- For surface mount applications
- Low profile package
- Easy pick and place
- Ultrafast recovery times for high efficiency
- Low forward voltage, low power loss
- Built-in strain relief, ideal for automated placement
- High temperature soldering: 250°C/10 seconds on terminals
- Plastic package has underwriters laboratories flammability classification 94V-0



MECHANICAL DATA

- Case: JEDEC DO-214AC, molded plastic body over passivated chip
- Terminals: Solder Plated, solderable per MIL-STD-750, Method 2026

Maximum Ratings (@TA = 25°C unless otherwise specified)

Characteristic	Symbol	MURA120T3G	UNITS
Marking code		MURA120T3G	
Maximum recurrent peak reverse voltage	V_{RRM}	200	V
Maximum RMS voltage	V_{RWS}	140	V
Maximum DC blocking voltage	V_{DC}		V
Maximum average forward rectified current at $T_L=90^\circ\text{C}$	$I_{F(AV)}$	2.0	A
Peak forward surge current 8.3ms single half sine-wave super imposed on rated load(JEDEC Method)	I_{FSM}	50	A

Thermal Characteristics

Characteristic	Symbol	MURA120T3G	UNITS
Typical junction capacitance at 4.0V, 1MHZ	C_J	50	pF
Maximum thermal resistance (NOTE1)	$R_{\theta JA}$ $R_{\theta JL}$	40 15	$^\circ\text{C/W}$
Operating temperature range	T_J	-55----- +150	$^\circ\text{C}$
Storage temperature range	T_{STG}	-55----- +150	$^\circ\text{C}$

Electrical Characteristics (@TA = 25°C unless otherwise specified)

Characteristic	Symbol	MURA120T3G	UNITS
Maximum instantaneous forward voltage at 2.0A	V_F	1.0	V
Maximum DC reverse current @TA=25°C	I_R	10.0	μA
at rated DC blocking voltage @TA=125°C		350	
Maximum reverse recovery time at $I_F=0.5\text{A}$ $I_R=1.0\text{A}$ $I_{rr}=0.25\text{A}$	t_{rr}	50	ns

NOTE: 1.P.C.B.mounted on 0.2X0.2"(5.0X5.0mm) copper pad area

FIG.1 – FORWARD CURRENT DERATING CURVE

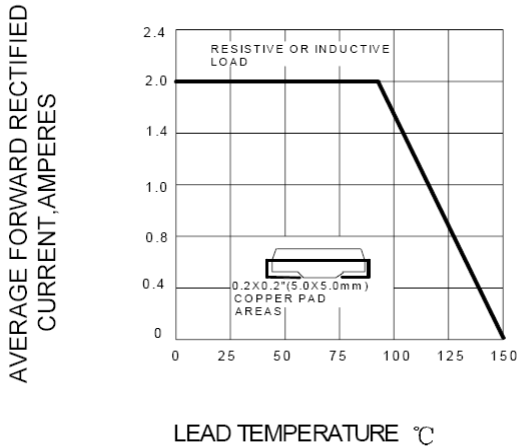


FIG.2 – MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

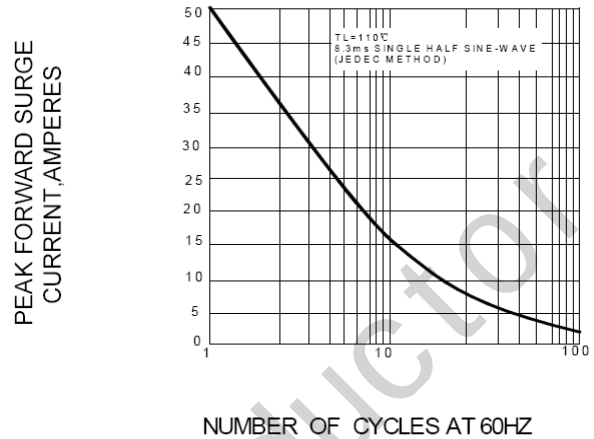


FIG.3 – TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

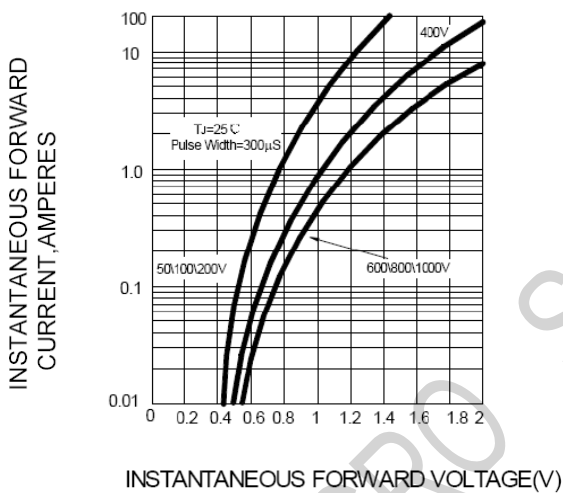


FIG.4 – TYPICAL REVERSE CHARACTERISTICS

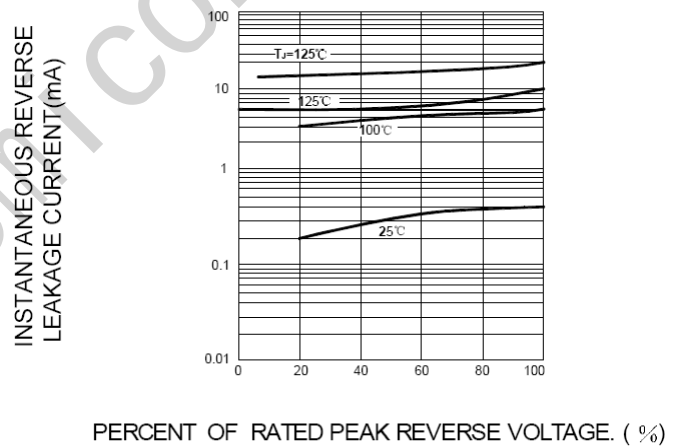


FIG.5 – TYPICAL JUNCTION CAPACITANCE

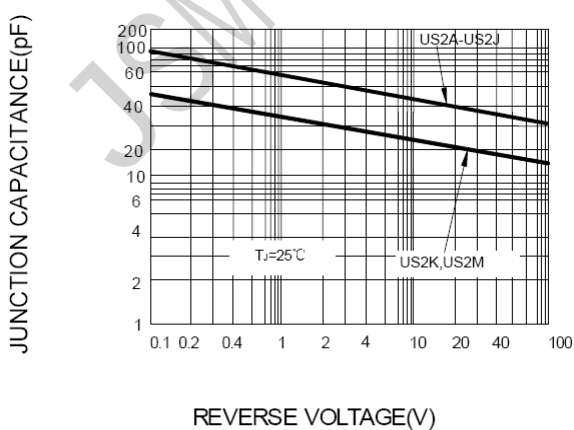
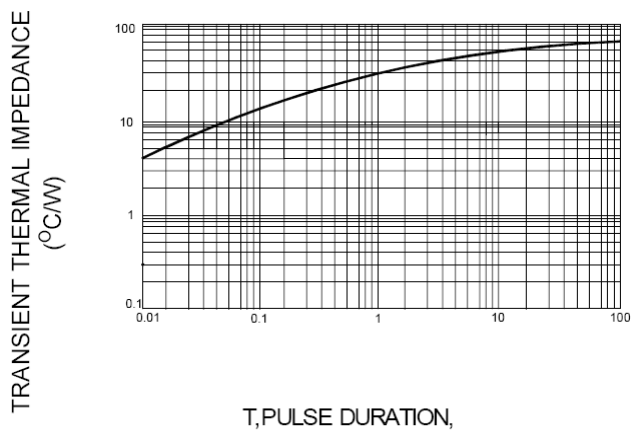
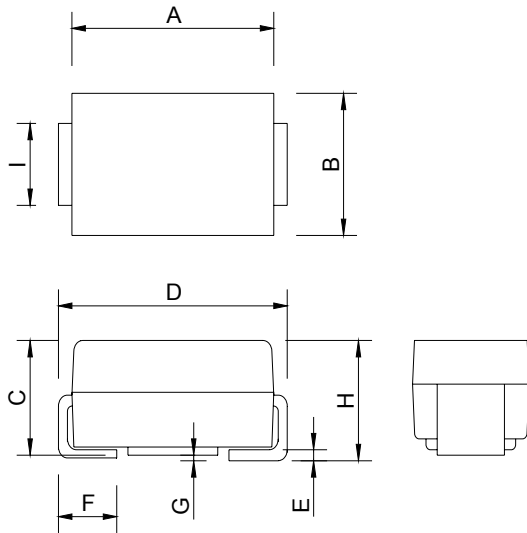


FIG.6 – TYPICAL TRANSIENT THERMAL IMPEDANCE

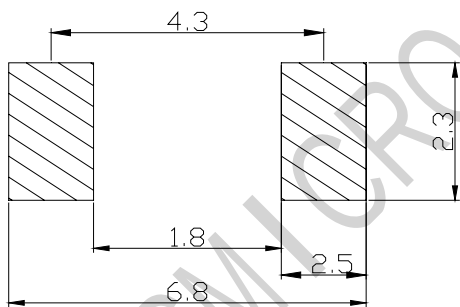


PACKAGE OUTLINE DIMENSIONS



DO-214AC(SMA)		
Dim	Min	Max
A	4.30	4.70
B	3.30	3.70
C	2.00	2.30
D	5.05	5.55
E	0.10	0.30
F	0.95	1.55
G	0.20MAX	
H	2.10	2.50
I	1.85	2.15
All Dimensions in mm		

SOLDERING FOOTPRINT



Unit : mm

单击下面可查看定价，库存，交付和生命周期等信息

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